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# P-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
- 100	0.450 at V <sub>GS</sub> = - 10 V	-1.5	8.1		
- 100	0.557 at V <sub>GS</sub> = - 4.5 V	-1.2	0.1		

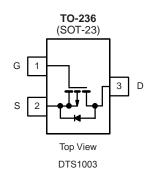
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET<sup>®</sup> Power MOSFET
- Ultra Low On-Resistance
- Small Size



#### **APPLICATIONS**

• Active Clamp Circuits in DC/DC Power Supplies



<b>ABSOLUTE MAXIMUM RATINGS</b>	$T_A = 25$ °C, unle	ss otherwise r	noted	
Parameter	Symbol	LIMIT	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 100		
Gate-Source Voltage	$V_{GS}$	± 20	V	
Continuous Drain Current (T, = 150 °C) <sup>a, b</sup>	T <sub>A</sub> = 25 °C	1	- 1.5	
Continuous Drain Current (1 <sub>J</sub> = 150 °C) <sup>a, a</sup>	T <sub>A</sub> = 70 °C	- I <sub>D</sub>	- 1.2	
Pulsed Drain Current		I <sub>DM</sub>	- 4.5	Α
Continuous Source Current (Diode Conduction) <sup>a,</sup>	I <sub>S</sub>	- 6.8		
Avalanche Current	L = 1.0 mH	I <sub>AS</sub>	2.2	
Avalanche Energy	L = 1.0 Min	E <sub>AS</sub>	1.31	mJ
Mariana Bana Birata da ah	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.75	W
Maximum Power Dissipation <sup>a, b</sup>	T <sub>A</sub> = 70 °C		0.48	] vv
Operating Junction and Storage Temperature Ran	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maniana karatia ta Andria (8	t ≤ 5 s	<b>D</b>	85	150		
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	$R_{thJA}$	140	186	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	45	60	]	

#### Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



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			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 100			V	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	- 1.2		- 2.5	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zoro Cata Valtago Brain Current	l	V <sub>DS</sub> = - 80 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 2.6			Α	
	В	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$	0.45 0.60		0.60		
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -0.5 \text{ A}$		0.557	0.75	Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 0.5 A		2.1		S	
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> = - 1.0 A, V <sub>GS</sub> = 0 V		0.5	- 1.2	V	
Dynamic <sup>b</sup>	•		•	•			
Total Gate Charge	$Q_g$	V <sub>DS</sub> = -80 V, V <sub>GS</sub> = 10 V,		8.1	13		
Gate-Source Charge	Q <sub>gs</sub>	$I_{DS} = -0.5 \text{ A}$		1.6		nC	
Gate-Drain Charge	Q <sub>gd</sub>			2.4		1	
Gate Resistance	$R_g$	f = 1.0 MHz		10		Ω	
Input Capacitance	C <sub>iss</sub>			570	689		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		136		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			27			
Switching <sup>c</sup>							
Torre On Time	t <sub>d(on)</sub>			8			
Turn-On Time	t <sub>r</sub>	$V_{DD}$ = - 75 V, R <sub>L</sub> = 75 Ω $I_{D} \cong$ - 1.0 A, $V_{GEN}$ = - 10 V		14		ns	
Turn O# Time	t <sub>d(off)</sub>	$R_{a} = 6 \Omega$		17			
Turn-Off Time	t <sub>f</sub>	g – • 22		11		1	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		90		nC	

#### Notes:

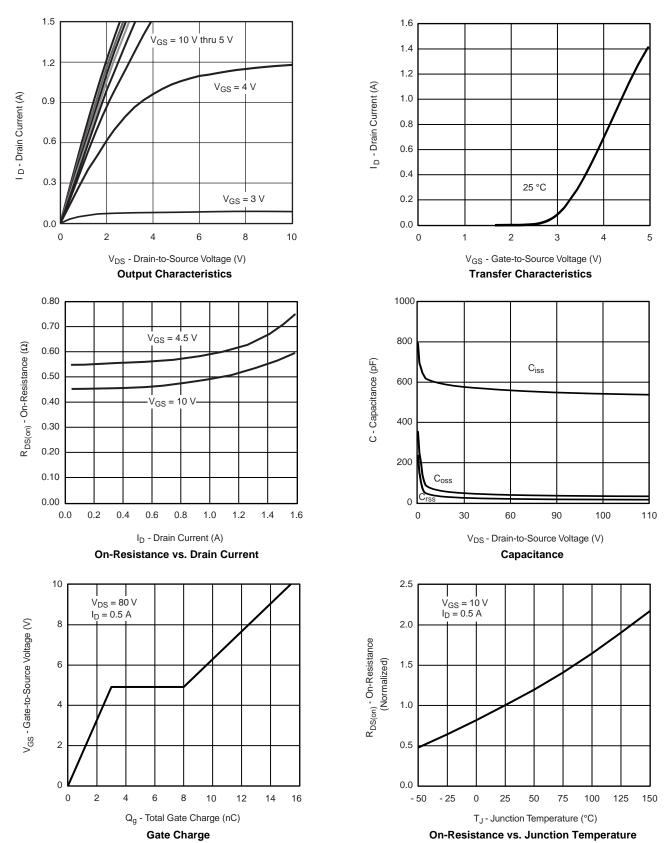
- a. Pulse test: PW  $\leq$  300  $\mu s$  duty cycle  $\leq$  2 %.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





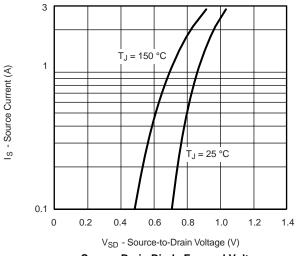
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



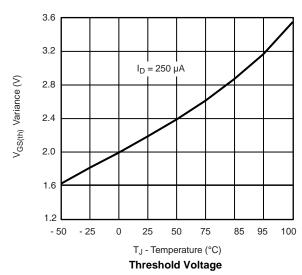


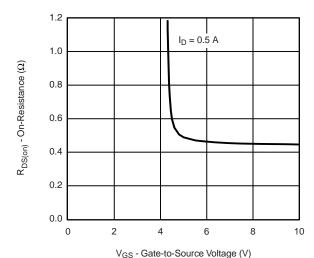


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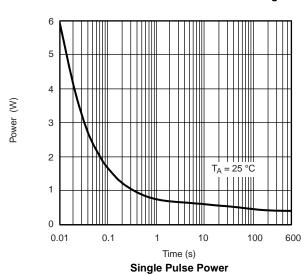


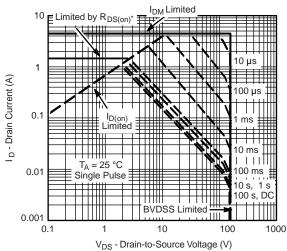
#### Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage



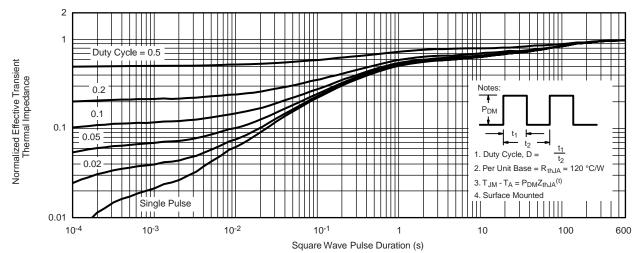


\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area



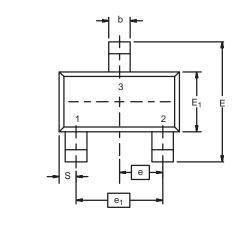
## **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

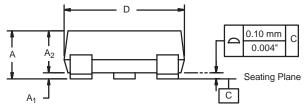


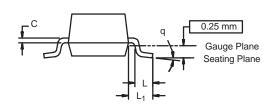
Normalized Thermal Transient Impedance, Junction-to-Ambient



## SOT-23 (TO-236): 3-LEAD







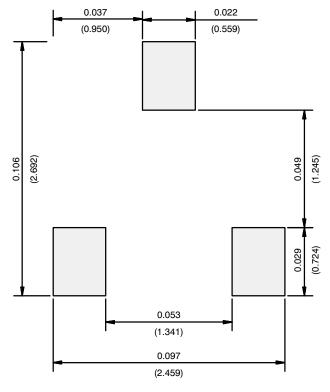
Dim -	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.074	0.0748 Ref	
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025	Ref	
S	0.50 Ref		0.020	Ref	
q	3°	8°	3°	8°	

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)





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